

# PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Shawn He	06/10/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Sony Computer Entertainment Inc.
<b>Street Address:</b>	1-7-1 Konan
<b>Internal Address:</b>	Minato-ku
<b>City:</b>	Tokyo
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	108-0075
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13160348
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(619)235-0398
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	6192381900
<b>Email:</b>	docketing@procopio.com
<b>Correspondent Name:</b>	PROCOPIO, CORY, HARGREAVES & SAVITCH LLP
<b>Address Line 1:</b>	525 B STREET
<b>Address Line 2:</b>	SUITE 2200
<b>Address Line 4:</b>	SAN DIEGO, CALIFORNIA 92101
<b>ATTORNEY DOCKET NUMBER:</b>	114514-027UTL
<b>NAME OF SUBMITTER:</b>	Andrew Klapoetke-Reese
<b>Total Attachments: 1</b> source=Assignment#page1.tif	

CH \$40.00 13160348

501564938

**PATENT**  
**REEL: 026444 FRAME: 0150**

Attorney Docket No.: 114514-027UTL  
Client Ref. No.: SCEA10088US00

### ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in REAL-TIME DATA MONITORING BASED ON DATA PUSH (Application Number \_\_\_\_\_, Filing Date: \_\_\_\_\_) for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address (The undersigned hereby authorizes and requests the attorneys of Procopio, Cory, Hargreaves & Savitch LLP, Customer No. 27189 to insert in the appropriate blanks, the serial number and filing date of the application when known);

AND WHEREAS, SONY COMPUTER ENTERTAINMENT INC., a corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, 108-0075 Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, their successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or their designee(s), as ASSIGNEE or their successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at their own expense;

And I further agree that ASSIGNEE will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment is executed on the date(s) indicated below.

Shawn He  
\_\_\_\_\_  
Name of first inventor

San Diego, CA  
\_\_\_\_\_  
Residence of first inventor

  
\_\_\_\_\_  
Signature of first inventor

6/10/11  
\_\_\_\_\_  
Date of Assignment